

ABSTRACT

The present invention provides a resin-type conductive paste composition which uses a silver-based powder as a conductive powder, and which enables a cured product thereof to have a favorably decreased volume resistivity. A conductive paste composition according to the present invention is configured such that: a conductive powder (A) is a silver-based powder that uses at least silver; a resin component (B) is at least one of a thermosetting resin and a thermoplastic resin; and additionally, an ester compound (C) that comprises an ester structure represented by general formula (1) or (2), while having a molecular weight within the range of from 150 to 2,000, or a salt of the ester compound (C), or a specific ether/amine compound (D) having a molecular weight within the range of from 150 to 30,000 is contained therein. (In the formulae, one of X¹ and X² represents Cl or Br, and the other represents Cl, Br, H or OH.)

